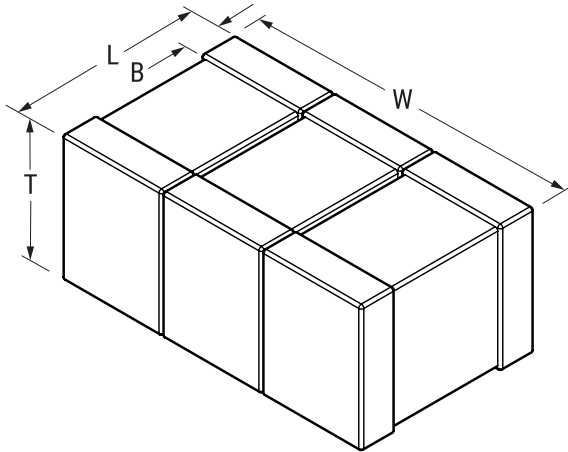




Click [here](#) for the 3D model.

General Information

Series	KONNEKT Comm U2J
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Chip Size	1812-3
Shelf Life	78 Weeks
MSL	1

Dimensions

L	4.5mm +/-0.3mm
W	5.3mm +/-0.6mm
T	3.2mm +/-0.3mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	2200

Specifications

Capacitance	1.4 uF
Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	U2J
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0.1% Loss/Decade Hour
Insulation Resistance	714.29 MOhms

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